

REV.	LOCAS.	DESCRIPTION	DATE	DRAWN
01		INITIAL RELEASE.		

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.20mm

1.3 Shell: copper alloy,t=0.25mm

2.Specification:

2.1 Current rating: 1 A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

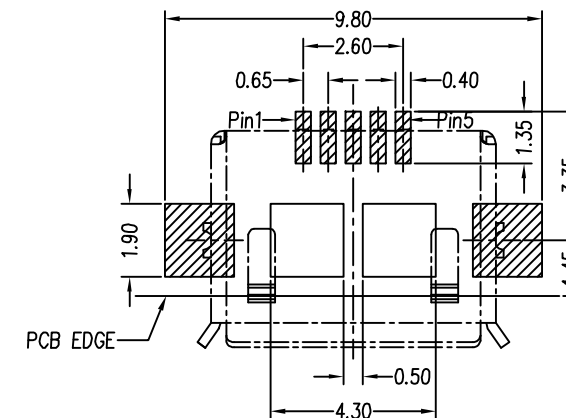
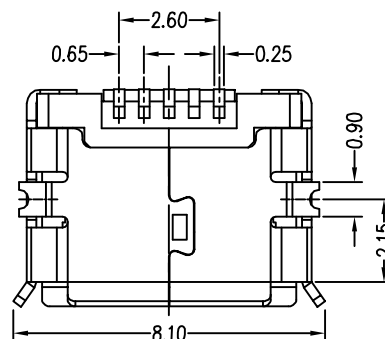
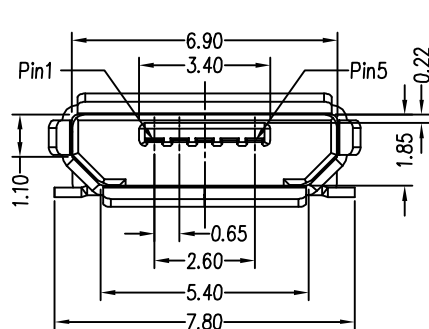
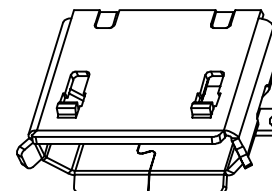
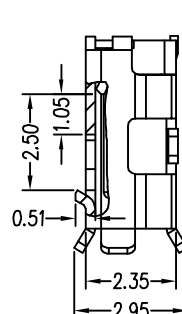
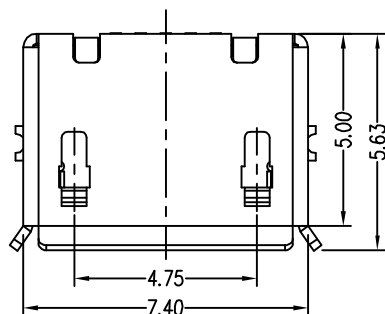
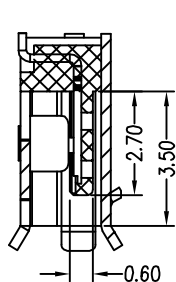
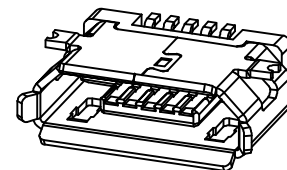
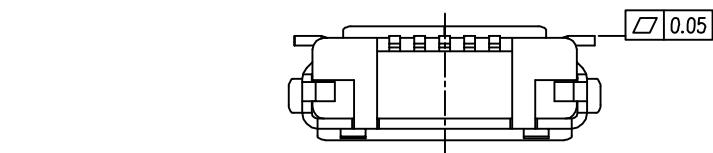
2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05

Kgf Min.after 10000 insertion/extraction cycles

2.7 Temperature range: -30°C~80°C



RECOMMENDED PCB LAYOUT



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PART NO.	MUSB05F-85629	DRAWN	MARK
DWG NO.		CHECK	JOHN
TOLERANCE	X.±0.30 .X±0.25	APPROVE	MELODY

TITLE: MICRO USB 5S B型无柱有导位 铜壳

REV. A0

.XX±0.15 .XXX±0.10

SCALE 1:1

UNIT mm

NO

DESCRIPTION